

IEEE EPS in EPTC 2024, Singapore

Dec 5th, 2024

Invited talk #2

Title: Glass Core Substrate Market and Opportunity

Speaker: Tan Yik-Yee, Yole Group

Bio:

Dr. Tan Yik-Yee is a Senior Technology & Market Analyst, Semiconductor Packaging at Yole Group, within the Semiconductor Manufacturing & Global Supply Chain Business Line. Yik Yee Tan holds a Ph.D. in Engineering from Multimedia University (MMU, Malaysia). She has more than 25 years of experience in semiconductor packaging. Based on her technical expertise and market knowledge, she develops technology & market reports and is engaged in dedicated custom projects. Prior to Yole, Yik Yee Tan worked as a failure analyst and interconnect principal at Infineon Technologies (Malaysia) and later as an open innovation senior manager at Onsemi (Malaysia). While at Onsemi, Yik Yee was deeply involved in numerous innovative advanced packaging projects. She published more than 30 papers and hold 3 patents.

Abstract:

Glass core substrate gained a lot of attention since Intel announced the planning to adopt this material in September 2023. Intel said, "Glass substrates help overcome limitations of organic materials by enabling an order of magnitude improvement in design rules needed for future data centers and Artificial Intelligence (AI) products." It is clear, hype in demands for AI is the mega trends of this century. It requires a system with higher transmission speeds and bandwidths. The organic substrate is facing the challenge to meet future system requirement. Introducing glass core substrate material as alternative to overcome the bottleneck of organic substrate is promising. This presentation will share the glass core substrate opportunity in different market. In depth discussion on the challenges and opportunities. Last, how the supply chain reaction and readiness.



- IEEE EPS Malaysia has supported EPTC 2024, Singapore on Dec 5th 2024.
- IEEE EPS Past Chair, Dr YY Tan, who is also from Yole Intelligence, has presented an invited talk on "Glass Core Substrate Market and Opportunity".
- The conference room was packed with >100 participants who were actively listening to the emerging glass material as another preferred candidate for IC Substrate core material to get ready for future Generative AI requirement with larger form factor and smaller L/S requirement.

